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SUBMINIATURE SOLID STATE LAMP

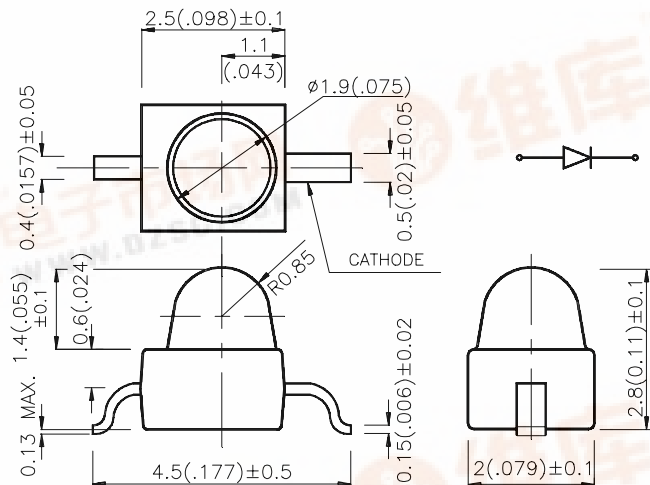KM2520MGC03   MEGA GREEN

Features

●SUBMINIATURE PACKAGE.

●WIDE VIEWING ANGLE.

●GULL WING.

●LONG LIFE - SOLID STATE RELIABILITY.

●LOW PACKAGE PROFILE.

●PACKAGE : 1000PCS / REEL.

Description

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions

Notes:

1. All dimensions are in millimeters (inches).

2. Tolerance is ±0.25(0.01") unless otherwise noted.

3. Lead spacing is measured where the lead emerge package.

4. Specifications are subject to change without notice.

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Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
KM2520MGC03	MEGA GREEN (InGaAlP)	WATER CLEAR	100	400	20°

Note:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Mega Green	574		nm	IF=20mA
λD	Dominate Wavelength	Mega Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Halfwidth	Mega Green	26		nm	IF=20mA
C	Capacitance	Mega Green	20		pF	VF=0V;f=1MHz
V_F	Forward Voltage	Mega Green	2.1	2.5	V	IF=20mA
I_R	Reverse Current	Mega Green		10	uA	VR = 5V

Absolute Maximum Ratings at T_A=25°C

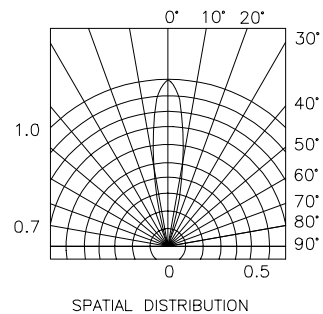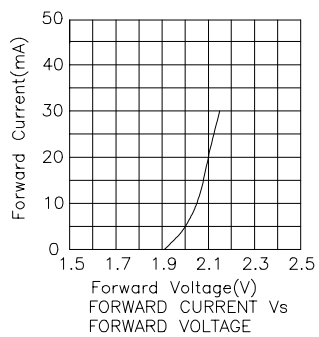| Parameter	Mega Green	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	205	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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$T_A = 25°C$
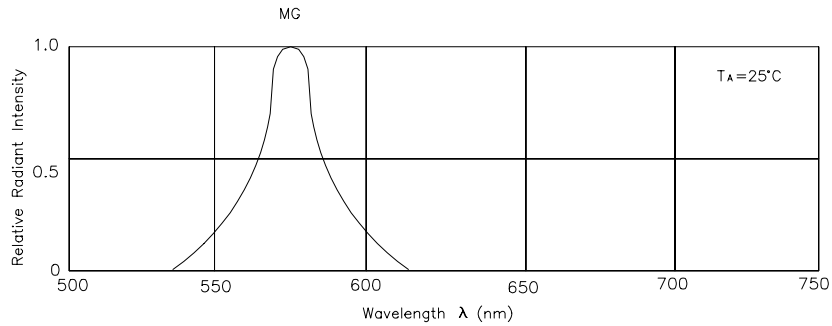
RELATIVE INTENSITY Vs. WAVELENGTH

Relative Radiant Intensity

Wavelength λ (nm)

Mega Green KM2520MGC03

Forward Current(mA)

Forward Voltage(V)
FORWARD CURRENT Vs
FORWARD VOLTAGE

Luminous Intensity
Relative Value at IF=20mA

I_F—Forward Current (mA)
LUMINOUS INTENSITY Vs.
FORWARD CURRENT

Forward Current (mA)

Ambient Temperature T_A (°C)
FORWARD CURRENT
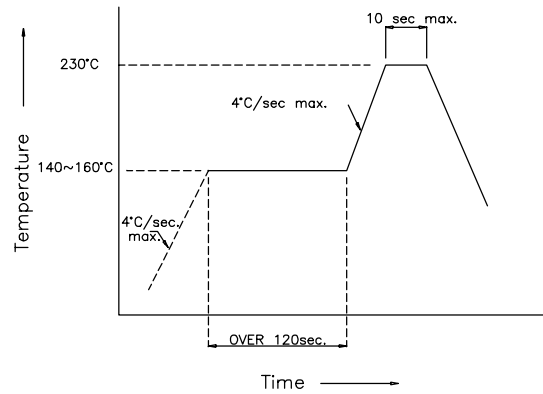DERATING CURVE
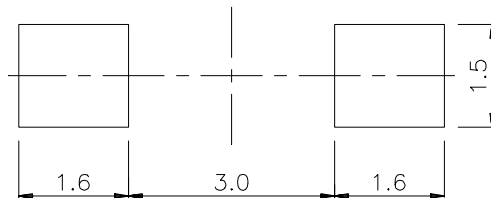
SPATIAL DISTRIBUTION
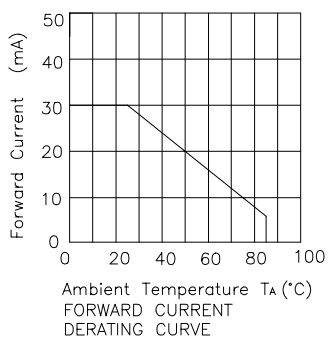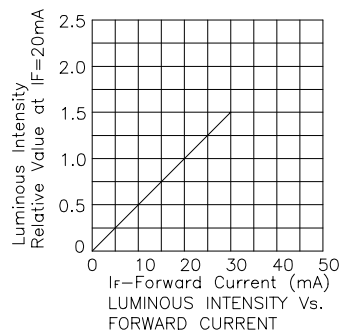
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KM2520MGC03
SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling
process to normal temperature is required between first and
second soldering process.

Recommended Soldering Pattern
(Units : mm)

Tape Specifications
(Units : mm)